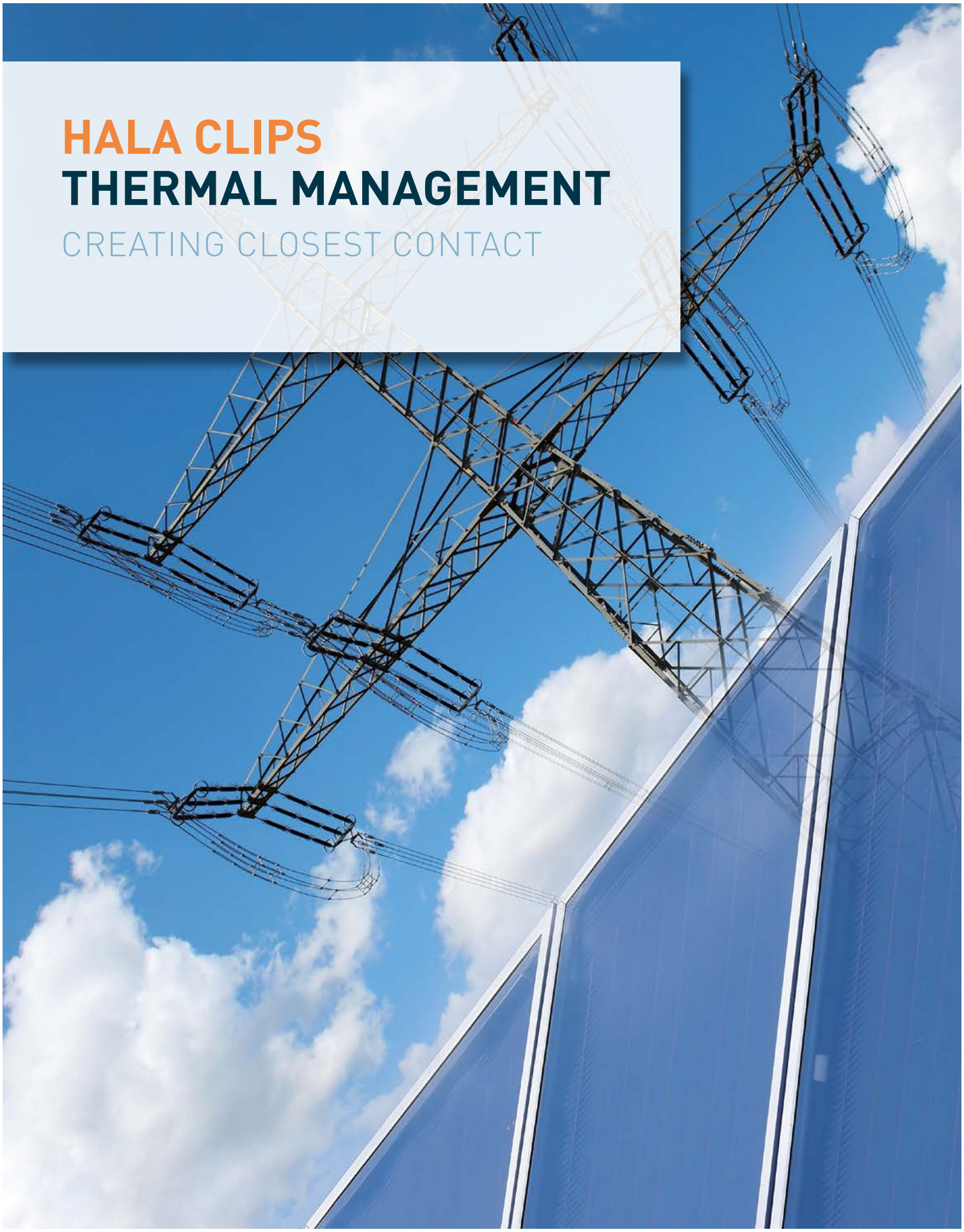
HALA

HALA CLIPS
THERMAL MANAGEMENT

CREATING CLOSEST CONTACT



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THERMAL MANAGEMENT

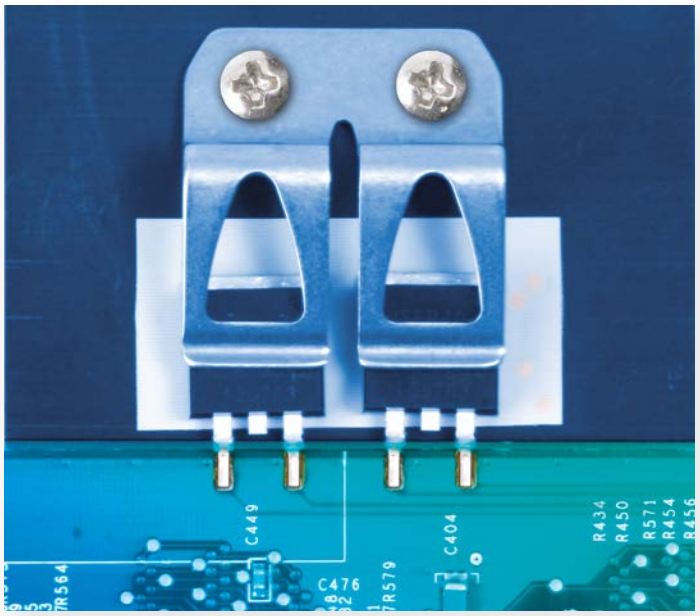
CREATING CLOSEST CONTACT

BENEFITS

- Maximized thermal contact (even at minimum package height)
- FE-simulation optimised stress behaviour
- Optimized interaction with HALA Thermal Interface Materials
- Mounting friendly design
- Easy chip identification by apertures

We design your tailor-made clip solution.

Please contact us as your development partner.

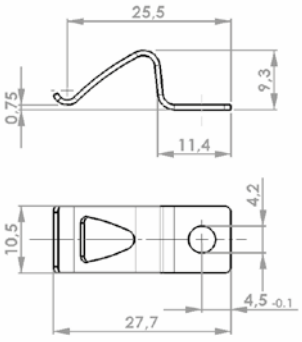


Release 04 / 2020

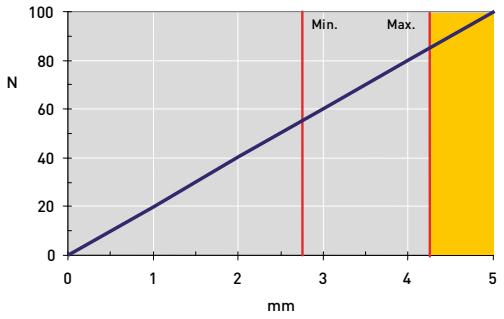
HALA CLIP TO 220-1

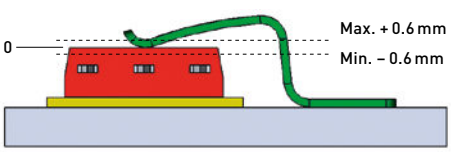
- Force range: ca. 55...85 N
- Pressure range: ca. 35...55 N/cm² (50...80 PSI) for different types of TO 220 packages (Surface area TO 220 approx.1.6 cm²)

Dimensions



FORCE VS. DEFLECTION

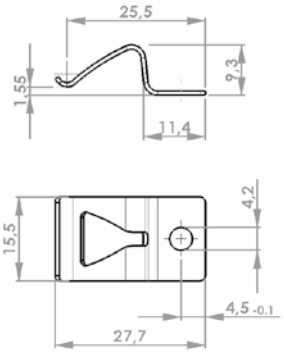




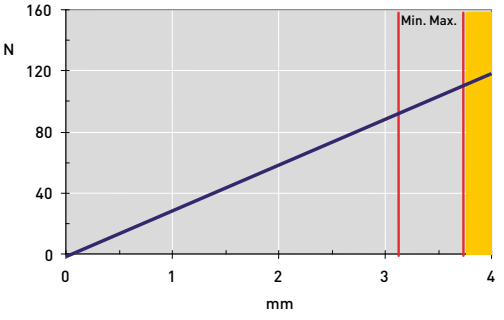
HALA CLIP TO 247-1

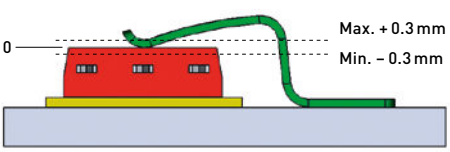
- Force range: ca. 95...110 N
- Pressure range: ca. 28...32 N/cm² (40...47 PSI) for different types of TO 247 packages (Surface area TO 247 approx. 3.4 cm²)

Dimensions



FORCE VS. DEFLECTION





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